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UTILITY PATENT APPLICATION TRANSMITTAL UNDER 37 CFR §1.53(b)

Attorney Docket Number	50126/002001
Applicant	MICHAEL D. GILBERT
Title	ELECTRICALLY DISBONDING MATERIALS

APPLICATION ELEMENTS:

Cover sheet	1 page
Specification	38 pages
Claims	10 pages
Abstract	1 page
Drawing	9 pages
Combined Declaration and POA, which is: <input checked="" type="checkbox"/> Newly signed for this application	2 pages
Small Entity Statement, which is: <input checked="" type="checkbox"/> Newly signed for this application;	1 page
Recordation Form Cover Sheet and Assignment	3 pages
Return Receipt Postcard	1

FILING FEES:

Basic Filing Fee: \$380	\$380
Excess Claims Fee: $72 - 20 = 50 \times \$9$	450
Excess Independent Claims Fee: $8 - 3 = 5 \times \$39$	195
Multiple Dependent Claims Fee: \$130	130
Total Fees:	\$1155

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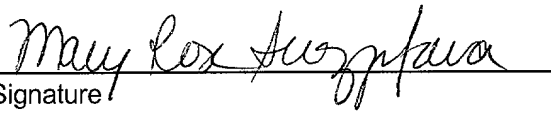
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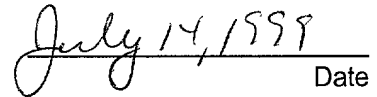
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Applicant or Patentee : Michael D. Gilbert
 Serial or Patent No. : Not Yet Assigned
 Filed or Issued : HERewith
 Title : ELECTRICALLY DISBONDING MATERIALS

**VERIFIED STATEMENT (DECLARATION) CLAIMING SMALL ENTITY STATUS
 (37 CFR 1.9(f) and 1.27(c)) - SMALL BUSINESS CONCERN**

I hereby declare that I am

- ☐ the owner of the small business concern identified below:
☒ an official of the small business concern empowered to act on behalf of the concern identified below:

Name of Small Business Concern: EIC Laboratories

Address of Small Business Concern: 111 Downey Street, Norwood, MA 02062

I hereby declare that the above identified small business concern qualifies as a small business concern as defined in 13 CFR 121.12, and reproduced in 37 CFR 1.9(d), for purposes of paying reduced fees to the United States Patent and Trademark Office, in that the number of employees of the concern, including those of its affiliates, does not exceed 500 persons. For purposes of this statement, (1) the number of employees of the business concern is the average over the previous fiscal year of the concern of the persons employed on a full-time, part-time or temporary basis during each of the pay periods of the fiscal year, and (2) concerns are affiliates of each other when either, directly or indirectly, one concern controls or has the power to control the other, or a third party or parties controls or has the power to control both.

I hereby declare that rights under contract or law have been conveyed to and remain with the small business concern identified above with regard to the invention, entitled **[**TITLE OF APPLICATION**]** by inventors **[**FULL NAMES OF ALL INVENTORS**]** described in

- ☒ the specification filed herewith.
☐ application serial no. **[**SERIAL NUMBER**]**, filed **[**FILING DATE**]**.
☐ patent no. **[**PATENT NUMBER**]**, issued **[**ISSUE DATE**]**.

If the rights held by the above identified small business concern are not exclusive, each individual, concern or organization having rights to the invention is listed below and no rights to the invention are held by any person, other than the inventor, who would not qualify as an independent inventor under 37 CFR 1.9(c) if that person made the invention, or by any concern which would not qualify as a small business concern under 37 CFR 1.9(d), or a nonprofit organization under 37 CFR 1.9(e). *NOTE: Separate verified statements are required from each named person, concern or organization having rights to the invention averring to their status as small entities. (37 CFR 1.27)

Assignee Name:

Assignee Address:

☐ INDIVIDUAL ☐ SMALL BUSINESS CONCERN ☐ NONPROFIT ORGANIZATION

I acknowledge the duty to file, in this application or patent, notification of any change in status resulting in loss of entitlement to small entity status prior to paying, or at the time of paying, the earliest of the issue fee or any maintenance fee due after the date on which status as a small entity is no longer appropriate. (37 CFR 1.28(b))

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application, any patent issuing thereon, or any patent on which this verified statement is directed.

Name: Stuart F. ^{C SFC} Logan

Title: Vice President, Advanced Materials

Address: 111 Downey Street
 Norwood, MA 02062

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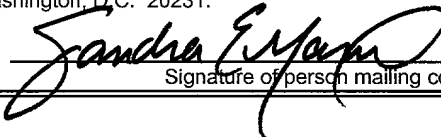
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APPLICATION
FOR
UNITED STATES LETTERS PATENT

APPLICANT : MICHAEL D. GILBERT
TITLE : ELECTRICALLY DISBONDING MATERIALS

ELECTRICALLY DISBONDING MATERIALS

5 **Statement as to Federally Sponsored Research**

This invention was made with United States government support under Contract No. F08635-97-C-0036 awarded by the U.S. Department of the Air Force. The United States government has certain rights to this invention.

Background of the Invention

10 The invention relates to materials for use as coatings and adhesives that may be disbanded from a surface to which they are applied without harm to that surface. The invention further relates to methods of disbanded adhesives and coatings from substrate surfaces.

Adhesive bonds and polymeric coatings are commonly used in the
15 assembly and finishing of manufactured goods. Adhesive bonds are used in place of mechanical fasteners, such as screws, bolts and rivets, to provide bonds with reduced machining costs and greater adaptability in the manufacturing process. Adhesive bonds distribute stresses evenly, reduce the possibility of fatigue, and seal the joints from corrosive species. Similarly, polymer-based coatings are
20 commonly applied to the exterior surface of manufactured products. These coatings provide protective layers that seal the surface from corrosive reactants, as well as provide a painted surface that can be more aesthetically pleasing.

Among the best adhesives and coatings in terms of strength and durability are those based on thermosetting polymers. Typically applied as a
25 liquid mixture of low molecular weight monomers, these adhesives wet and penetrate pores on the substrate surface. On cure, insoluble and infusible

crosslinked polymers are formed that are mechanically interlocked and often covalently bound to the substrate to which they are applied. Common amine-cured epoxies are a typical example of adhesives and coatings that employ thermosetting mixtures.

5 Although adhesive bonds offer many advantages over mechanical fasteners, adhesive bonds are essentially permanent. There are no methods available for ready disassembly of adhesively bonded objects. The separation strategies that do exist typically involve time-consuming chemical procedures requiring high temperatures and aggressive chemicals. Examples of such
10 techniques are described in U.S. Patent No. 4,171,240 by Wong and U.S. Patent No. 4,729,797 by Linde *et al.* These techniques, although generally effective, are quite harsh and can damage the objects being separated, making them unsuitable for many applications.

 Similarly, conventional coating materials, such as polyurethanes,
15 epoxies, phenolics, melamines, and the like, are essentially permanent. Such coatings are often removed with an aggressive chemical agent that is applied to the coating surface to degrade the coating material. Mechanical abrasion, such as sand blasting or wire brushing, is also employed. Although these techniques are effective in removing the polymer coating, they are time and labor intensive, as
20 well as being quite harsh and likely to cause damage to the underlying surface.

 To provide materials that are more easily removed from a substrate, the prior art describes adhesives formed from reactive monomers containing linkages susceptible to chemical degradation. Such materials are described in U.S. Patent Nos. 5,512,613 and 5,560,934 to Afzali-Ardakani *et al.* and in U.S. Patent No.
25 4,882,399 to Tesoro *et al.* Additionally, S. Yang *et al.* in "Reworkable Epoxies:

Thermosets with Thermally Cleavable Groups for Controlled Network Breakdown”, *Chem. Mater.* **10**:1475 (1998) and Ogino et al. in “Synthesis and Characterization of Thermally Degradable Polymer Networks”, *Chem. Mater.* **10(12)**:3833 (1998) describe curable resins containing thermally labile linkages.

- 5 Other polymers containing thermally labile or thermally reversible crosslinks are described in U.S. Patent No. 3,909,497 to Hendry et al. and U.S. Patent No. 5,760,337 to Iyer et al. An alternative approach to bond cleavage is described in U.S. Patent No. 5,100,494 to Schmidt which discloses embedding a nichrome heating element within a thermoplastic so that the adhesive softens or melts upon
10 resistive heating. Although these specially prepared materials are more readily cleaved from the substrate, they still require conditions that are harsh to delicate substrates or adjacent adhesive bonds.

- Thus, there remains a need in the art for a material capable of being disbonded selectively and precisely under mild conditions. Such a material would
15 provide adhesive bonds and coatings that could be employed in a variety of applications where facile removal of the material from the surface is desired.

Summary of the Invention

- The present invention provides a composition capable of strong, yet temporary, substrate bonding or coating that is removable without damage to the
20 underlying substrate. It may be used in both temporary and permanent bonding and coating applications.

An electrochemically disbondable composition of the invention includes a matrix functionality and an electrolyte functionality. The matrix functionality provides an adhesive bond to a substrate, and the electrolyte functionality provides

sufficient ionic conductivity to the composition to support a faradaic reaction at an interface with an electrically conductive surface in contact with the composition.

The adhesive bond is weakened at the interface on application of an electrical potential across the interface. In preferred embodiments, the disbondable

5 composition is a phase separated material having first regions of substantially matrix functionality and second regions of substantially electrolyte functionality.

The “matrix functionality” of a material is the ability of a material or a mixture of materials to join by mechanical or chemical bonding to a substrate and to adhere to the substrate by virtue of this bond. Matrix functionality also provides
10 mechanical strength to the material, such that the material is capable of transferring load between substrates or, as a coating, is self-supporting.

The “electrolyte functionality” of a material is the ability of the material to conduct ions, either anions, cations or both. The ions are provided by a salt added to the material or are chemically incorporated into the material as an
15 ionomer, that is, a polymer containing ionized groups. The electrolyte functionality is understood to derive from the ability of the composition to solvate ions of at least one polarity.

The term “faradaic reaction” means an electrochemical reaction in which a material is oxidized or reduced.

20 The term “adhesive” refers to polymer-based materials which are capable of holding materials together by surface attachment. An adhesive typically forms a bond to a substrate by mechanical interlocking and often covalent bonding to the substrate. The adhesive is chemically distinct from the bonded substrate and the bonded materials may be dissimilar from one another.

25 In one embodiment of the invention, the matrix functionality is provided

by a polymer selected from the group consisting of epoxies, phenolics, acrylics, melamines, maleimides, and polyurethanes.

In another embodiment of the invention, the polymer has a variable crosslink density to form regions of low crosslink density having a relatively high ionic conductivity and regions of high crosslink density having a relatively high mechanical strength.

In another embodiment of the invention, the polymer includes coordination sites that are capable of solvating ions and that support the electrolyte functionality of the composition.

In other embodiments, the electrolyte functionality is provided by an electrolyte additive selected from the group consisting of ionically conductive monomers, oligomers and polymers, and ionomers and may be localized in regions within said polymer to form a secondary phase of high ionic conductivity and mobility.

In one preferred embodiment, the disbondable composition is an adhesive, and may have a lap shear strength in the range of 2000-4000 psi. In another preferred embodiment, the composition is a coating, and may be resistant to delamination from a substrate to which it is applied.

In another aspect of the invention, an electrochemically disbondable composition is provided having an uncured polymeric material having an electrolyte located therein. The uncured polymeric material, when cured, provides in combination with the electrolyte, sufficient solubility and mobility to the electrolyte to support a faradaic reaction at a surface in electrical contact with an electrode.

Another aspect of the invention includes a corrosion resistant coating in

which a substrate subject to corrosion has as a coating a composition having a matrix functionality and an electrolyte functionality, said matrix functionality providing an adhesive bond to said substrate, and said electrolyte functionality providing sufficient ionic conductivity to said composition to support a faradaic
5 reaction at an interface with said substrate. Corrosion of the substrate does not propagate at the interface.

In yet another aspect of the invention, a bonded structure includes two electrically conductive surfaces, and a bond between the two surfaces composed of the electrochemically disbondable composition of the invention. The conductive
10 surface may be an article or articles to be secured by the bond or they may be a conductive element selected from the group consisting of sheets, foils, grids and meshes. The conductive element further may be bonded to an article using a conventional adhesive or the disbondable composition of the invention.

In one embodiment of the invention, the electrically conductive surface
15 is an electrically conductive coating applied to a substrate, which may be non-electrically conducting.

In another embodiment of the invention, the bonded structure includes first and second electrically conductive surfaces; and an electrically conductive element disposed therebetween. The electrochemically disbondable composition
20 of the invention is used to bond the electrically conductive element to the first and second conductive surfaces.

A laminate structure is also provided which is particularly advantageous in the joining of irregular or non-conductive surfaces. The laminate includes first and second electrically conductive elements selected from the group consisting of
25 foils, sheets, meshes and grids, and the disbondable composition of the invention

disposed therebetween and bonded to the first and second elements.

In another aspect of the invention, a method is provided for disbonding a composition from an electrically conductive surface to which it is bonded. The method includes providing a first electrically conductive surface treated with the electrochemically disbondable composition of the invention, contacting a second electrically conductive surface to the composition, and passing an electric current through the disbondable composition to cause a faradaic reaction at the surface, whereby the bond to the surface is weakened.

The bond between the disbondable composition and a substrate may be weakened in a short time by the flow of electrical current across the bondline between the substrate and the composition. Typically, the bond is weakened sufficiently that the substrate is separated easily by hand from the disbondable composition. At least one of the substrates separates cleanly and is substantially free from any residual bonding composition. Because the disbonding procedure uses electricity instead of heat or chemical reagents, inadvertent disbonding during normal use is unlikely.

Brief Description of the Drawing

The invention is described with reference to the figures which are presented for the purpose of illustration only and which are not limiting of the invention, and in which:

Figure 1 is a cross-sectional illustration of a bonded joint using the composition of the invention and of the disbonding operation of the invention;

Figure 2 is a cross-sectional illustration of an embodiment of the invention incorporating a conductive foil into a bonded structure;

Figure 3 is a cross-sectional illustration of an embodiment of the invention incorporating a conductive coating into a bonded structure;

Figure 4A-C are illustrations of bonded articles of the invention incorporating electrically conductive sheets or coatings in the bonded structure;

5 Figure 5 is an illustration of a bonded joint and electrical circuitry for simultaneous disbonding at more than one interface in a bonded joint; and

Figure 6A is a perspective drawing and 6B is a cross-sectional illustration of a laminate bonded structure.

Description of the Preferred Embodiments

10 The electrochemically disbondable composition of the invention possesses matrix functionality and electrolyte functionality, where the electrolyte functionality provides sufficient ionic conductivity to support a faradaic reaction at an electrically conductive substrate in contact with the composition. The matrix
15 functionality of the disbondable composition provides the adhesive or coating properties needed for its intended use, while the electrolyte provides the ionic conductivity and ion mobility needed to maintain the faradaic reaction.

The electrically conductive substrate may be a surface of the article being bonded or coated. Alternatively, the electrically conductive substrate may be one added to the coating or bond to provide an electrochemically cleavable
20 surface.

The adhesive property of the composition is disrupted by the application of an electrical potential across the bondline between the composition and substrate. While not bound to any particular mode of operation, the faradaic reactions which take place at the composition/substrate interface are presumed to

disrupt the interaction between the disbondable material and the substrate, thereby weakening the bond therebetween. Disruption at the adhesive interface may be the result of a number of processes taking place at the interface, such as chemical degradation of the disbondable material, gas evolution at the substrate interface and/or material embrittlement, possibly by changes in crosslink density of the disbondable composition.

Matrix functionality may be provided by one of the general classes of polymers and polymer resins used in bonding or coating surfaces. The materials may be prepared from commercially available polymer resins, often without modification.

The polymer may be a thermoset polymer, which provides high strength and solvent resistance to the bond or coating, but which is difficult to remove from the surface. A thermoset polymer is one in which a linear or crosslinked network extends throughout the final composition to provide a polymer that is stable to heat and that does not flow or melt. The polymer is typically formed by *in situ* reaction or curing of lower molecular weight species, e.g., epoxies, or by the chemical transformation of soluble precursor polymers, e.g., formation of polyimide from polyamic acid. Exemplary thermosetting polymers include highly condensed polyimides, polyurethanes, epoxies, phenolic resins, urea or melamine formaldehyde condensates, acrylic resins and alkyd resins. A preferred polymer resin for use as an adhesive or a coating is epoxy.

The polymer may also be a thermoplastic which is thermally tractable and can be made to soften or flow with the application of heat. These polymers are linear or lightly branched and are typically soluble in some solvent. Exemplary thermoplastic polymers include acrylics, styrene/butadiene block copolymers and

the like.

The above polymers are well suited to provide the matrix functionality of the composition; however, in order to support a faradaic reaction at an electrically conductive substrate, the disbonding composition also must possess sufficient ion conductivity to permit ion transport within the composition. Modification of the polymer to promote or support ionic conductivity or to promote ion solubility therefore is contemplated.

In one embodiment of the invention, the polymer includes ion-coordinating moieties that are capable of solvating ions, and in particular cations, of the electrolyte. Exemplary ion-coordinating moieties include alkoxy groups, such as methoxy or ethoxy, and oligoethers, such as polyethylene oxide and the like, disulfide moieties, thioalkyl groups, alkyl or alkenyl nitrile groups and polyvinylidene fluoride groups. By way of example only, an epoxy resin may be cured using a diamine having a high alkoxy content to provide additional oxygen sites for cation coordination. Example 2 describes the use of the diamine, 4,7,10-trioxy-1,13-tridecanediamine, for this purpose.

Another manner in which the polymer supports or promotes the dissolution and diffusional movement of the ions found in the electrolyte is to have a glass transition temperature T_g that is below the disbonding temperature. This can be achieved by increasing the disbonding temperature, or adding a plasticizer to the polymer composition. The term "plasticizer" means an electrochemically stable additive which tends to reduce the crystallinity or order of the composition. Exemplary plasticizers include alkyl carbonates, low molecular weight alkoxides, cyclic esters, alcohols, nitriles, amides and ureas. Many other plasticizers well-known to skilled artisans may also be employed advantageously to lower T_g . It

can be additionally advantageous if the plasticizing molecules are capable of solvating ions, as are the above-mentioned exemplary plasticizers. By solvating ions, the plasticizer additive increases the concentration of salts that may be added to the composition to provide ionic conductivity (see below).

5 Heterogeneous curing can also be used to affect a low T_g . A heterogeneously cured thermosetting resin is one in which the crosslink density or degree of polymer condensation varies throughout the composite resulting in regions of high and low glass transition temperatures. This may be achieved by locally varying the amount of crosslinking or curing agent in the polymer.

10 In one embodiment of the invention, a heterogeneously cured polymer is obtained by adding a component to the polymer resin which serves as a reservoir for excess curing agent or crosslinking agent. Exemplary reservoirs include porous ceramics such as zeolites, clays or polymer gels. By way of example only, a zeolite may be infused with an excess of amine curing agent and mixed into an
15 epoxy polymer resin. The presence of the excess amine during a thermally activated cure results in the formation of a heterogeneous material having local regions of high amine content and low crosslink density near the zeolite particles embedded in a matrix of stoichiometric, high crosslink density material. Ideally, the regions of low crosslink density connect to form continuous pathways with
20 lower glass transition and higher ionic conductivity.

 In some embodiments of the invention, the electrochemically disbondable composition includes a separate electrolyte phase to provide the electrolyte functionality of the disbondable composition. An electrolyte may be used in combination with any of the above-mentioned polymers. The electrolyte
25 may be an ionically solvating molecule, including a plasticizer, or an oligomer or

polymer also capable of solvating ions. Typically, ion solvation is obtained with polar molecules or molecules that are easily polarized. The electrolyte may also constitute a portion or region of a polymer which is added to the composition. For example, the disbondable composition may include a block or graft copolymer having regions of high ionic conductivity and regions having some other desirable property, such as compatibility with the polymer resin. The polymer resin-miscible domains promote dispersion of the block copolymer throughout the entire resin, with the polar, ionically conductive regions associating into domains or micelles. Without the polymer resin-miscible domains, certain combinations of polymer and electrolyte may not be sufficiently compatible to form a cohesive composition and mechanical and/or adhesive strength would be compromised.

The electrolyte functionality of the disbondable composition provides ionic conductivity sufficient to maintain a faradaic reaction at an interface with an electrically conductive surface. Sufficient conductivity may be readily established by preparing a composition and applying a voltage across a bondline with an electrically conductive substrate. If current flow is observed, a faradaic reaction at the bondline may be assumed. Sufficient ionic conductivity also may be empirically observed by applying a voltage across the bondline and noting whether the bond is weakened. Compositions with ionic conductivities in the range of 10^{-11} to 10^{-5} S/cm² at room temperature are considered within the scope of the invention. Materials having higher ionic conductivities require shorter disbonding times. Compositions with ionic conductivities in the range of 10^{-9} to 10^{-7} S/cm² at room temperature are preferred.

The electrolyte is desirably ionically conductive and capable of supporting ion diffusion of a salt solvated therein. In most embodiments, complex

ion salts are added to the composition to provide ionic conductivity. Suitable salts include alkali metal, alkaline earth and ammonium salts. Preferred salts include polyatomic, high dissociation constant anions, such as hexafluorophosphate, tetrafluoroborate, hexafluoroantimonate and perchlorate.

5 In another embodiment, the electrolyte functionality is provided by an ionomer. The ionomer is a polymer or oligomer with ionized groups that provide ions capable of being solvated in the composition.

 The electrolyte is included in the disbondable composition in an amount sufficient to provide the requisite ionic conductivity to support the faradaic
10 reaction of the disbonding process. The actual amount of electrolyte used in a particular composition is dependent on the ionic conductivity of the polymer and the ability of the electrolyte to form a continuous conductive pathway within the composition. While a continuous pathway is not absolutely required, it promotes the efficiency of the process. Where ions are required to tunnel through regions of
15 higher resistance, higher voltages and longer times are required for disbonding.

 In preferred embodiments, approximately equal volumes of the matrix polymer and the electrolyte are used, although a wider range of compositions is contemplated as within the scope of the invention. Those skilled in the art are aware that a wide range of compositions may be used to obtain a substantially
20 continuously conductive electrolyte phase depending upon the materials used and how the composition phase separates. In some instances, a seemingly high level of electrolyte, e.g., 50 vol%, may be added without overly compromising the adhesive or mechanical properties of the disbondable composition. The composition is presumed to maintain its strength due to the ionic strengthening
25 typically observed in polymeric systems containing salts or ionomers. Ionic

domains may form, acting as pseudo-crosslinks in the ionically conductive regions or as crosslinks between the conductive region and the matrix polymer.

In preferred embodiments, the disbondable composition is a phase-separated composition having regions enriched in electrolyte having high ionic conductivity and regions enriched in matrix polymer having high mechanical or bonding strength. A phase-separating composition may comprise an initially miscible mixture of polymer resin and electrolyte. The electrolyte may segregate from the growing resin network during cure. Phase separation may be encouraged by increasing the molecular weight of the polymer resin, oligomeric (or polymeric) electrolyte additive, or both.

In preferred embodiments, phase separation results in regions having high ionic conductivity forming a continuous pathway within the composition. Without a continuous pathway, ions are required to traverse the high strength, low conductivity regions of the material during electrochemical disbonding.

Bicontinuous or interpenetrating networks advantageously provide a continuous ionically conductive pathway without compromise to the mechanical strength of the adhesive polymer resin. Phase-separated compositions having the desired microstructure may be obtained by varying the relative proportions of the various components of the disbondable composition. For example, a composition comprising approximately equal parts by volume of polymer and electrolyte may cure to provide a continuous ionically conductive pathway.

A preferred electrolyte additive for formation of a phase-separated microstructure is a graft copolymer having a backbone with a low affinity for the polymer resin and pendant polymer blocks of high ionic conductivity. The low affinity backbone serves as a nucleation point for phase separation by generating

small non-solubilized domains within the pre-cured resin, while the high ionically conductive pendant polymer blocks interact with the matrix polymer resin. During cure, the ionically conductive polymer phase separates from the curing resin and grows around the low solubility domains which results in a well dispersed and continuous network. An exemplary graft copolymer includes a siloxane backbone grafted with amine-terminated poly(ethylene glycol) pendant blocks. A graft copolymer may be a comb polymer. The comb polymer is a graft copolymer in which blocks or pendant oligomeric chains of a dissimilar polymer are more or less regularly repeated along the polymer backbone.

In a further embodiment of the invention, the cohesive strength of the disbonding composition may be enhanced through the use of ionically modified oligomers (as the electrolyte component). For example, amine-functionalized oligomers (such as the amine-terminated poly(siloxane)-graft-poly(ethylene glycol) described above) may be converted to the corresponding ammonium salt by ion exchange of the amino group with an ammonium cation. The resulting highly viscous electrolyte is readily miscible with polymer resins, and in particular with amine-curable epoxy resins. A mixture of approximately equal volumes of the ion-exchanged electrolyte and epoxy resin can be cured to form a high cohesive strength adhesive material possessing sufficient ionic conductivity to support electrochemical disbonding.

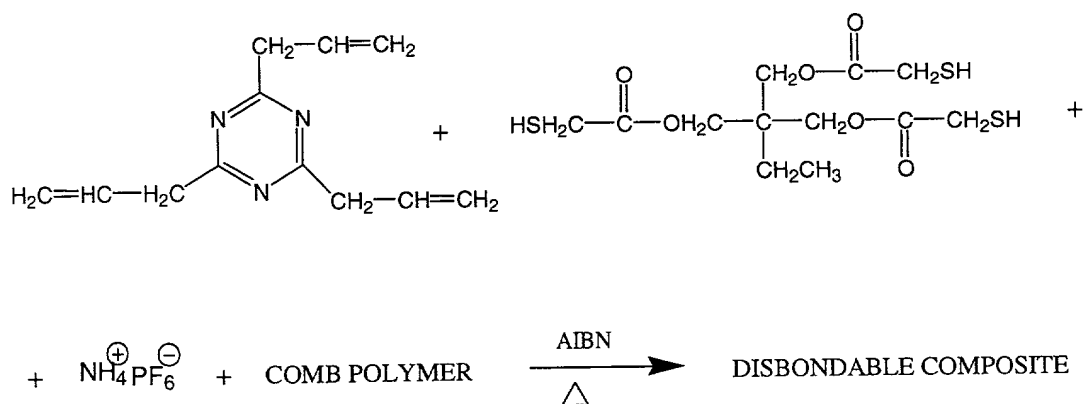
While the invention has been described primarily with reference to epoxides, other polymer resins may be used in accordance with the invention.

For example, bismaleimides may be directly substituted for epoxies in the electrochemical disbondable formulations. Selection of the appropriate bismaleimide is made to ensure adequate phase separation of the polymer matrix

phase from the ionically conducting phase. The highly polar, ion coordinating ability of the cyclic imide group may result in compatibilizing ionic interactions occurring between the two phases. To overcome this, the bismaleimide can be modified to decrease its polarity in order to increase cure-induced phase

5 separation. These adjustments are made empirically to achieve phase separation, while controlling the phase dimensions and degree of mechanical connectedness between the phases.

Admixtures of a comb polymer, such as those described above, with monomers of thiols and trienes according to eq. 1 would also yield a homogeneous
10 mixture. Free radical polymerization by thermal decomposition of azobis(isobutylnitrile) (AIBN) would result in network polymer formation and phase separation of the comb polymer. Control of phase morphology, dimension and interphase interaction are also mediated by inclusion of ammonium salt modified alkyl thiols.



Equation 1

In another embodiment of the invention, phenolic or melamine resins are used for the disbondable material of the invention. Self-condensing resins such as phenolics or melamine (urea) /formaldehyde may be modified with ionically conductive oligomers or polymers and then cured to form phase separated

5 materials provided that the ionically conductive additive contains no functionalities that will condense with formaldehyde. Phase separation is controlled by adjusting the moieties present in the matrix resin and ionically conductive additive to favor late-stage phase separation and possibly by pre-seeded nucleation using compatible/incompatible copolymer blocks, as is discussed
10 hereinabove. Ionic modification, most likely using sulfonate or ammonium groups to both the matrix resin and ionically conductive additive, could be used to control phase morphology, dimension and interphase reactions.

It is understood that additives may be included in a disbonding composition so long as they do not compromise the bonding strength or ionic
15 conductivity of the composition. Exemplary additives include pigments for color, corrosion inhibitors, leveling agents, gloss promoters and fillers. Other polymer resin additives, known to those of skill in the art, such as rubber tougheners, e.g., poly(acrylonitrile-*co*-butadiene), may be added to increase electrolyte solubility or enhance other desirable properties of the resin. The disbondable composition
20 further may include particles of a non-conducting material, e.g., crushed glass or plastic beads, to prevent conductive surfaces useful in the disbonding process from contacting each other and forming a short circuit. Other additives will be apparent to those skilled in the art and are within the scope of the invention.

The solubilizing ability of the uncured composition and the post-cured
25 composition may differ. Thus, initially soluble additives may be excluded from

the composition as it cures. In some embodiments, additives may be selected for incorporation into the disbondable composition to retain their solubility in the cured polymer. In other embodiments, differing pre- and post-cured solubilities may be used to advantage in obtaining phase-separated materials (see below).

5 The disbondable compositions may be used as adhesives. A bonded joint may be obtained by disposing a disbondable composition between two or more surfaces such that the composition forms an adhesive bond to each surface and holds each surface in a generally fixed position relative to the other surfaces while maintaining those positions in response to a force equal to at least the weight
10 of the lightest bonded element.

 A bonded joint may be obtained by applying an adhesive of the invention to a suitable surface as a solution, a melt or a reactive mixture. Solvents, if used, may be removed by evaporation prior to mating the substrates or may be absorbed by the coated substrate. Compositions applied as a melt, a solution or a
15 reactive mixture wet the substrates and then solidify in order to achieve a high level of adhesion. When applied as a reactive mixture, the composition undergoes a curing reaction that converts the fluid-like mixture to a solid. The latter method of application is typically used for common two-component adhesives, such as conventional epoxies.

20 The disbondable material of the invention may also be applied as a coating to a substrate surface. Due to the material's anti-corrosive properties (discussed hereinbelow), it is advantageously employed as an undercoating or primer layer. As in the formation of a bonded joint, the disbondable material may be applied to a suitable surface as a solution, a melt or a reactive mixture. It is
25 within the scope of the skilled artisan to prepare formulations suitable for coating

applications.

The strength of an adhesive bond may be determined in various ways. Typically, lap shear strengths are used as a measure of the strength of an adhesive bond. Shear strength is the force required to separate two overlapping plates when pulling in a direction parallel to the plane of the plates. Following ASTM procedure D-1002, an Instron tester or suitable alternative instrument is used for this purpose. Bonds formed using disbondable compositions are capable of high strength, having shear strengths of greater than 200 psi, preferably on the order of 1000 psi, and more preferably 2000 psi and as high as 4000 psi. Disbondable compositions employing epoxies for matrix functionality generally provide shear strengths in the range of 2000-4000 psi using this configuration. This is comparable to the shear strengths of conventional epoxy resins. Thus, it is possible to form an electrochemically disbondable joint without compromise to the mechanical strength of the bonded materials.

As described previously, ionic conductivity is a necessary feature of the disbondable composition. The rate of the disbonding faradaic reaction, and hence the time necessary to achieve the desired level of bond weakening, is determined by the ionic current flowing through the composition. This current can be measured in the external circuit using an ammeter. The magnitude of the current is small, typically less than 1 mA/cm² of bonded area when the disbonding voltage is initially applied. The current further decreases with time, often decaying to 0.2 mA/cm² or less after one minute. Although the relationship between current and disbonding voltage is not strictly linear, the use of higher disbonding voltages results in higher currents and more rapid disbondment. Likewise, the use of low disbonding voltages results in longer disbondment times. The practitioner may

select a disbonding voltage from a few volts to greater than 100 volts depending on the desired disbondment time and other considerations such as safety and the need to prevent damage to voltage-sensitive substrates.

The disbondment time at a particular disbonding voltage also depends on the ionic conductivity of the composition. Higher ionic conductivities permit higher currents at a given voltage and correspondingly support an increase in the rate of the disbonding reaction. However, the disbonding reaction occurs substantially at the interface between the composition and the substrate and the amount of faradaic charge (the time integral of the faradaic current) required to effect disbondment is very small. Therefore, to achieve disbonding in a practical period of time requires only a small current and the level of ionic conductivity which is needed to support this activity is relatively low. This feature is advantageous because the formulation of materials with high ionic conductivity leads to poor adhesive properties and limited mechanical strength.

The magnitude of ionic conductivity suitable for the disbonding process may be understood by measurement of the ionic conductivity of the disbondable composition described in Example 3. Ionic conductivity is determined using the AC impedance technique in which the complex impedance of the composition is measured over a wide frequency range ($5\text{-}10^5$ Hz) and the data is fit to a simple circuit model. This method has been previously described; see, MacDonald et al., *J. Electroanal. Chem.* **200**:69-82 (1986). Values for ionic conductivity as a function of temperature are listed in Table 1.

Table 1. Conductivity measurements

Temperature (°C)	Conductivity (S/cm)
0	1.1×10^{-8}
20	2.3×10^{-7}
40	1.6×10^{-6}
60	7.0×10^{-6}
80	2.1×10^{-5}

Although the conductivities listed in Table 1 for the composition of Example 3 are considerably smaller than conductivities of electrolytes used in electrochemical devices (ca. 10^{-3} S/cm), the conductivity is sufficient to achieve disbonding in 10 minutes at room temperature with an applied voltage of 50 V.

The foregoing embodiments teach a disbondable composition having matrix and electrolyte functionalities which permit controlled disbonding of the composition from an electrically conductive substrate in response to an electrical voltage applied between the substrate and composition.

With reference to Figure 1, a method includes passing an electrical current through a disbondable composition **10** in contact with electrically conducting substrates **12**, **14** to disrupt the bonding at an adhesive/substrate interface **16** and thereby weaken the bond therebetween. Current is supplied to the composition using an electrical power source **18**. When an electrical voltage is applied between the two substrates **12**, **14**, electrochemical reactions occur at the substrate/disbonding composition interfaces. The electrochemical reactions are understood as oxidative at the positively charged or anodic interface and reductive

at the negatively charged or cathodic interface. The reactions are considered to weaken the adhesive bond between the substrates allowing the easy removal of the disbondable composition from the substrate. (Note, for the purposes of discussion in all Figures one of the electronically conductive surfaces is designated as the positive electrode. It is understood that the polarity of the system may be reversed.) The electrical power source may supply direct or alternating current. Direct current may be supplied from a battery or an AC-driven, DC power source.

Most disbonding processes require a voltage of only several volts, for example, less than 10 volts. However, higher voltages, e.g., on the order of up to 100 volts, may be useful to overcome the electrical resistance inherent in the system. Very little current, ca. 10^{-3} amps per square centimeter, is required to complete disbonding. Disbonding is accomplished rapidly, regardless of the complexity of the surface to be disbonded. In many cases, a potential is applied for a time period in the range of about 5 to 60 minutes, and preferably about 10 to 30 minutes.

The electrochemically disbondable composition may be selected so that disbonding occurs at either the positive or negative interface. The positive interface is the interface between the electrochemically disbondable composition and the electrically conductive surface that is in electrical contact with the positive electrode. Similarly, the negative interface is the interface between the electrochemically disbondable composition and the electrically conductive surface that is in electrical contact with the negative electrode. Disbonding occurs at the positive interface for the disbonding compositions described in Examples 1-4 below. By reversing current direction prior to separation of the substrates, the bond may be weakened at both substrate interfaces.

In an alternative embodiment, alternating current may be used to simultaneously disbond both substrate/adhesive interfaces. This embodiment is particularly useful when removal of the disbondable composition from both substrates after disbonding is desired. Typically, the alternating current reverses the anodic and cathodic interfaces on a time scale that is short compared with the total time necessary to disbond the interfaces. The current can be applied with any suitable waveform, provided sufficient total time at each polarity is allowed for disbonding to occur. Sinusoidal, rectangular, and triangular waveforms are appropriate. The waveform may be applied from a controlled voltage or a controlled current source.

Alternative formulations may be employed for cathodic disbonding. Such an embodiment is described in Example 7.

Non-conductive or non-conductively coated substrates may also be electrochemically disbanded by incorporation of an additional conducting element to complete the electrical circuit. With reference to Figure 2, a conducting element **20** is incorporated into the bonding structure in those instances when one of the substrates **22** is non-conductive or coated with a non-conductive layer. A voltage is applied between the conducting element **20** and an electrically conductive substrate **24** having a disbondable composition **10** disposed therebetween. Disbonding occurs at either conductive element/disbonding composition interface **26** or at substrate **24** depending on the arrangement of the electrical circuit and the choice of the composition. Conducting element **20** is bonded on its opposite face to the non-conducting substrate **22** by adhesive **28**, which may be either a conventional adhesive or the electrochemically disbondable composition of the invention. It is contemplated that the use of a conducting

element in joints and disbonding operations is not limited to non-conductive substrates and may also be used with conductive substrates.

The electrically conductive element may be any electrically conducting material capable of being embedded between two bonded surfaces. Exemplary elements include, but are not limited to, wire mesh, metal foil, and a conductive coating, e.g., a silver-filled epoxy. In those instances where the conductive element is a wire mesh or grid, the mesh size should provide adequate surface area contact for the disbondable material since bond weakening occurs in those areas in close proximity to the substrate.

Figure 3 illustrates an embodiment in which the conductive element is a conductive coating **30** coated onto the surface of the non-conductive substrate **22**.

The method of the present invention can also electrically cleave a bond between two electrically non-conductive substrates. Disbonding is accomplished by using a bonded structure incorporating two electrically conductive elements.

An electrical circuit is completed using the electrically conductive elements and disbonding occurs at the element. Figure 4 illustrates several bonded structures of the invention.

Figure 4A is a bonded structure incorporating two electrically conductive foils, meshes or grids, **40, 42**. The electrochemically disbondable composition **10** is disposed therebetween. The elements **40, 42** are bonded to substrates **44, 46**, respectively. Substrates **44, 46** may be conductive substrates, non-conductive substrates or substrates having a non-conductive coating, although the use of conductive elements is useful in those instances when both substrates are non-conductive. Conductive elements are bonded to the substrates using either conventional adhesives or the disbondable composition of the invention **64**.

Figure 4B is a bonded structure incorporating two electrically conductive coatings **48, 50**, which coat substrates **52, 54**, and which are in electrical contact through external wires with a power source to complete the electrical circuit. The electrochemically disbondable composition **10** is disposed therebetween. Substrates **52, 54** may be conductive substrates, non-conductive substrates or substrates having a non-conductive coating, although the use of conductive elements is useful in those instances when both substrates are non-conductive.

Figure 4C is a related bonded structure incorporating an electrically conductive foil, mesh or grid **42** and an electrically conductive coating **48** which coats substrate **52**. The electrochemically disbondable composition **10** is disposed between the conductive elements **42, 48**, which are in electrical contact through external wires with a power source to complete the electrical circuit. Substrates **46, 52** may be conductive or non-conductive, or substrates having a non-conductive coating. The use of conductive elements is advantageous in those instances when both substrates are non-conductive.

The disbonding operation may also simultaneously disbond more than one surface, using a setup such as that shown in Figure 5. The bonded structure includes a conductive element **42** disposed between two substrates **60, 62**.

Disbondable composition **10** is used in forming the bond. Substrates **60, 62** may be conductive substrates or they may incorporate conductive elements as described hereinabove to facilitate disbonding from non-conductive substrates. Both substrates are connected in parallel to the voltage source at the anode and the conductive elements serves as the cathode (in embodiments where anodic disbonding takes place). In operation, the anodic disbonding material/substrate

interfaces are cleaved, leaving a conductive elements coated on both sides with disbonding material.

A preferred embodiment of the invention includes a metal foil patch or laminate 69 such as that shown in Figure 6A. The patch includes a thin layer of electrochemically disbondable material 70, backed on either side by metal foils 72, 74 typically aluminum foil. The patch is flexible and readily conforms to nonplanar surfaces. The patch can be cut to size, coated with adhesive and placed between the substrates to be bonded. Similar to the bonded structures described above, bonded structures formed using a foil patch may be readily separated at the metal foil by passing an electrical current between the foils.

In all of the above structures and articles, contact may be made with the conductive substrate or element through conventional means. Clips or other contacting means may be employed. In preferred embodiments, a conductive tab may be spot welded onto the electrically conductive substrate or element to improve electrical contact.

In another embodiment of the invention, the composition may be formulated with specific curing agents such that the cured material is removed from a substrate using solvents that are comparatively benign to the environment and pose minimal health risk to the practitioner. This embodiment is particularly useful following electrical disbonding of a composition. Residual material of the composition that remains on a substrate following the disbonding can be readily removed without resort to aggressive chemicals, heat or mechanical means. Thus, for example, an adhesive composition that disbonds at the anodic electrode can be removed from the cathodic electrode using a solvent such as a low molecular weight alcohol, e.g. methanol, ethanol, or the like. Removal of the composition is

achieved by solvent swelling that is promoted by the rapid passage of the low molecular weight alcohol through the ionically conductive phase of the composition. A composition of this embodiment is described in Example 2.

The disbonding process may also be used to remove material which has been deposited on a substrate as a coating. For example, disbondable material is applied to a metal surface as a primer layer, over which a conductive film, such as silver-filled epoxy, and a suitable topcoat is applied. The coating is removed by attaching a power source to the metal surface (anode) and the silver-filled epoxy layer (cathode).

Alternatively, a conductive metal foil or plate may be contacted to the disbondable primer to serve as a cathode. The electrode serves as the cathode, for example, if the composition disbonds at the anodic interface. Contact is facilitated by placing an ionically conductive gel between the coating and the metal plate. Suitable gels comprise a polymer-thickened solution or liquid polymer electrolyte containing the same salt as is used in the disbonding adhesive, e.g., ammonium hexafluorophosphate.

In a previous embodiment, the use of compositions that could be swelled by a low molecular weight solvent were described. The same embodiment may also be usefully employed with coatings on a substrate. Swelling the ionically conductive phase of the composition with a low molecular weight solvent increases the ionic conductivity of the conductive phase, which promotes disbonding when an electrical voltage is applied between the substrate and coating.

This approach provides the possibility of selectively removing only a portion of the coating as disbonding only occurs where electrochemistry proceeds.

Provided that the conductive path through an individual bond is electrically

coated with a second paint layer. The second layer provides the principal water and salt barrier.

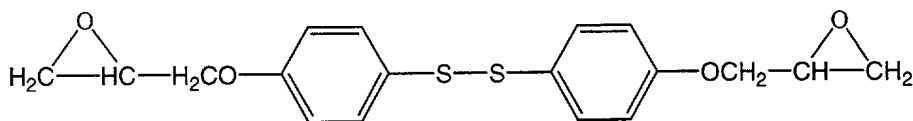
The inventive composition does not function as a corrosion resistant coating in the sense that it is a barrier layer. Rather, it functions as a corrosion resistant coating by preventing the spread of corrosion once it is initiated. It is hypothesized that the ionic osmotic pressure at the surface is reduced where it is in contact with the electrochemically disbondable material due to the presence of mobile ion species in the coating. Thus, the driving force for corrosive oxidation to propagate on the surface of the metal (ultimately leading to coating delamination) is eliminated or reduced.

An anti-corrosive coating therefore includes a primer layer comprised of the electrochemically disbondable material of the invention and a topcoat functioning as a protective barrier layer. If the barrier layer is compromised, the exposed metallic surface is susceptible to oxidation corrosion; however, the primer layer prevents its propagation underneath the coating and thereby prevents delamination of the coating.

The invention is illustrated in the following examples which are not limiting of the invention, the full scope of which is shown in the claims which follow the specification.

Example 1. This example describes an electrochemically disbondable composition using a plasticizer as the ionically conductive component.

A disulfide-linked diepoxide **1** of the following structure was synthesized according to the procedures outlined by Gilbert *et al* in *Mater. Res. Soc. Proc., Polymer/Inorganic Interfaces*, **304**:49 (1993).



1

An electrocleavable formulation was made by mixing 100 parts by weight of the above diepoxide with 30 parts of 4,7,10-trioxi-1,13-tridecanediamine and 10 parts of amine-terminated poly(acrylonitrile-*co*-butadiene), a rubber toughener (CAS 68683-29-4). To this mixture was added 20 parts each of 1-pentanol and ammonium hexafluorophosphate. The mixture reacted rapidly at room temperature to yield a cured resin which exhibited very high adhesive bond strengths to copper. This composition relied upon a combination of a plasticizer and chemical modification of the epoxy, e.g., incorporation of alkoxy-modified amine curing agent and acrylonitrile copolymer and also the disulfide epoxide to gain the requisite ionic conductivity in the product composition.

At room temperature, the ionic conductivity of this material is very low. However, the adhesive bond was electrochemically cleaved in 30 minutes by application of a 50-volt potential across the bond-line at elevated temperatures (60 °C).

This formation was also prepared as a solution in nitromethane which can be spray-coated onto substrates for bonding or coating. This solution has a pot-life of several hours, as compared to fifteen minutes for the epoxy mixture without solvent.

Example 2. This example describes an electrochemically disbondable composition using an ion exchanged graft copolymer, poly[dimethylsiloxane-*co*-methyl(3-hydroxypropyl)siloxane]-*graft*-poly(ethylene glycol) 3-aminopropyl ether, as the ionically conductive component.

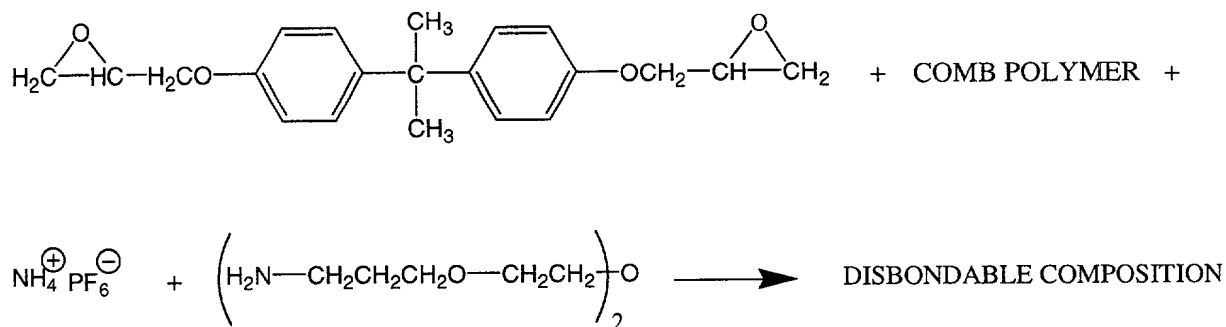
5 In a reaction vessel equipped with a mechanical stirrer, poly[dimethylsiloxane-*co*-methyl(3-hydroxypropyl)siloxane]-*graft*-poly(ethylene glycol) 3-aminopropyl ether (PMS-g-PEO) (75 g), an amine-functionalized comb polymer (CAS 133779-15-4) with a M_n of ca. 4000 was mixed with ammonium hexafluorophosphate (25 g, 0.153 mol) and the mixture was stirred at 70 °C for 12
10 hours under vacuum to allow the ion exchange reaction to proceed to completion. The resulting product was a viscous, transparent amber liquid.

A two-part epoxy resin was formulated using the above ion-exchanged PMS-g-PEO. Part A was formulated by blending 100 parts by weight ion-exchanged PMS-g-PEO with 75 parts by weight of a low molecular weight (M_n =
15 355) diglycidyl ether of bisphenol A (DGEBA) to form a viscous yellow liquid. The blending of the graft copolymer with an epoxy resin promotes dispersion of the electrolyte within the resin, which promotes an interpenetrating morphology of the two components of the adhesive composition. Part B was formulated by reacting 25 parts by weight of the DGEBA with 30 parts by weight of 4,7,10-
20 trioxa-1,13-tridecanediamine (CAS No. 4246-51-9) to form a chain-extended amine curing agent. Chain extension prereacts the epoxy resins to control the curing process and to provide parts of comparable weight in the two-part resin. Crushed glass (3 parts) and blue pigment (copper phthalocyanine) were added to Part B.

25 The unmixed two-part epoxy resin had a shelf-life of six months or more

at room temperature. It was mixed as a 3:1 ratio of Part A (yellow) to Part B (blue) to give a green-colored paste having a pot life of approximately one hour. The paste was applied between aluminum, copper and steel substrates to form bonded structures. The overall chemical reaction leading to the formation of the

5 disbondable composition is show in Eq. 2.



Lap shear tests were conducted using an Instron tester according to the specifications of ASTM D-1002, the results of which are reported in Table 2. Lap shear specimens were formed from 1 in. x 8 in. metal strips bonded together to have a one-half inch overlap.

10 **Table 2. Shear strength of bonded metal substrates.**

Substrate metal	break load (psi)
aluminum	1700-2200
steel	2200
copper	1600

15 These values are comparable to bonds formed using conventional epoxy resins. Thus, it is possible to form an electrochemically disbondable joint without

compromise to the mechanical strength of the bonded materials.

Lap shear tests were also performed to assess the effects of elevated temperature on the adhesive bond strength of bonded aluminum substrates formed using the formula of this example. The results are reported in Table 3.

Table 3. Shear strength of bonded aluminum substrates at various temperatures.

temperature (°C)	break load (psi)
50	1800
60	1400 (yield at 1000)
85	yield at 800

The bonded substrates were electrochemically cleaved at room temperature by applying a 50V potential between the metal substrates. Disbonding occurred at the anode. After 10 minutes, the substrates were easily snapped apart by hand. The anodic interface was substantially free of residual resin.

Residual material of the disbondable compositions prepared from 4,7,10-trioxi-1,13-tridecanediamine was removed from the cathode substrate using methanol.

Example 3. This example demonstrates the effect of substitution of the amine curing agent on the strength and disbonding function of an epoxy composition.

An epoxy resin was prepared as described in Example 2, with substitution of 4,7,10-trioxa-1,13-tridecanediamine with 15 parts tetraethylene pentamine (TEPA; CAS No. 112-57-2) to yield an electrocleavable composition

having bond strengths of up to 2500 psi to aluminum at both ambient and elevated temperatures. The disbonding conditions and rates were similar to those in Example 2. Disbonding occurred at the anode.

Example 4. This example demonstrates the effect of substitution of the ion-exchanged anion in PMS-g-PEO on the strength and disbonding function of an epoxy.

An epoxy resin was prepared as described in Example 2, with substitution of ammonium tetrafluoroborate for ammonium hexafluorophosphate to yield a resin that cured with increased hardness but with reduced room temperature conductivity. The observed increase in hardness is probably due to increased ionic crosslinking.

Anodic disbonding of this resin can be achieved by applying a 50V potential across the bondline for 40 minutes at room temperature. The longer disbonding time of the formulation with ammonium tetrafluoroborate is due to lower ionic conductivity of the material.

Example 5. This example demonstrates the effect of plasticizer incorporation into the composition on disbonding.

Ten parts octanol were added to the resin formulation of Example 3. Aluminum lap shear specimens bonded using the modified formulation exhibited shear strengths of 1600 psi and good mechanical properties. Application of a 50-volt potential at -20 °C resulted in disbonding in less than 15 minutes versus one hour for the unmodified version. At -40 °C, disbonding occurred in less than 12 hours versus no disbonding for the unmodified resin.

Thus, addition of plasticizer significantly improved the disbonding capability of the formulation at lower temperatures, which has significant practical

application where disbonding operations are required to take place outdoors or in other environmentally uncontrolled conditions. Presumably disbonding at room temperature will proceed significantly faster for the modified formulation.

Example 6. This example demonstrates increased ionic conductivity due to heterogeneous curing of the matrix polymer.

Trioxadodecane-1,13-diamine (80 parts by weight) was added to 13X zeolite powder (100 parts by weight) with stirring. The temperature of the mixture was allowed to increase as the amine adsorbed onto the surface and interior of the porous powder. Amine/zeolite complex (160 parts) were added to 100 parts DGEBA epoxy and 10 parts ammonium hexafluorophosphate. Samples made by bonding together aluminum substrates using this formulation were cured at 80 °C for one hour and exhibited good adhesive bond strength. The material exhibited moderate levels of ionic conductivity, about 1/10 that of the material of Example 2. Application of a 50-volt current for two hours at room temperature results in weakening of the adhesive bond.

Example 7. This example provides a composition disbondable at the cathodic interface.

Poly(propylene glycol)bis(2-aminopropyl ether) (PPODA, CAS No. 9046-10-1, M_n ca. 2000) was converted into the corresponding ammonium salt by an exchange reaction with ammonium hexafluorophosphate according to the reaction illustrated in Eq(1). To this end, PPODA (75 g) was mixed with ammonium hexafluorophosphate (25g) in a reaction vessel fitted with a mechanical stirrer and stirred for 48 hours at ambient temperature and pressure.

A blend containing 100 parts of ion-exchanged PPODA and 100 parts the disulfide epoxide of Example 1 was mixed with 8 parts dicyanodiamide. The

mixture formed a strong bond to aluminum when cured at 100°C for 4 hours. The bond can be electrochemically disrupted by applying a 50V potential across the bond for 30 minutes at 40°C. Disbonding occurs at the cathodic interface.

Example 8. This example describes disbonding from a non-conductive substrate using a conductive foil.

Aluminum foil (25 μm thick) was solvent degreased and etched with phosphoric acid and immersed in distilled water for one hour. Two sheets of the dried foil were then bonded together using the resin of Example 1 without crushed glass. The foil laminate was cured for one hour at 80 °C. The foil laminate **69** is illustrated in Figure 6A in which electrochemically disbondable composition **70** is sandwiched between foils **72**, **74**.

The foil laminate **69** was then further bonded between two substrates. The foil laminate was cut to size appropriate for the substrates to be bonded. The external surfaces of the foil were coated with an amine-cured disulfide epoxy resin that is not electrochemically disbondable. The sandwich structure is shown in Figure 6B, with conventional adhesive layers indicated as layers **76** and **78** (substrates not shown). The adhesive-coated laminate was disposed between two substrates and pressure was applied using weights or clamps to keep the assembly together. The assembly was cured at room temperature for a period of 24 hours, resulting in a high strength, permanent bond.

The substrates are disbonded by disrupting the bond at the foil/electrochemically disbonding adhesive interface **80**, which is indicated in Figure 6B. A 50V DC power source applied a potential difference across the bonded structure for 10 minutes, after which the structure could be snapped apart by hand. The foil was peeled off of the still-attached conventional epoxy layer.

The substrate was cleaned of the residual adhesive by soaking in a solution of ammonia water, sodium 3-mercaptopropyl sulfonate and methanol.

Example 9. This example describes disbonding from a non-conductive substrate using a conductive coating.

5 Non-conducting substrates were coated with a silver-filled epoxy. Connectors for external wiring were attached to the silver-filled epoxy. Following cure, a layer of electrochemically disbonding epoxy resin from Example 1 was coated over the silver-filled epoxy. The coated substrate surfaces were mated and the resin was cured, forming an adhesive bond. This bond was electrochemically
10 disbonded by attaching a 50V power source either directly to the silver-filled epoxy layers or to the connectors. Disbonding occurs in 20-40 minutes at room temperature, depending on the roughness of the silver epoxy.

Example 10. This example describes disbonding of a coating.

15 The resin from Example 1 was coated directly onto a low carbon steel surface as a primer layer. The coating can be applied from the bulk material or by spraying a 50 wt% solution of the uncured resin in a 1:1 mixture of nitromethane and methylene chloride. After drying, the primer layer was overcoated with a thin layer of silver-filled epoxy and a suitable topcoat. The ionically conductive primer layer provided exceptionally good wet adhesion under highly corrosive conditions.
20 Attachment of a 50V power source between the steel surface and the silver-filled epoxy resulted in disruption of the adhesive bond between the primer and the steel surface, allowing the coating to be easily removed by scraping. No corrosion was observed on the surface from which the coating was removed.

25 Example 11. This example describes another method of disbonding a coating using an electrolyte gel.

The resin from Example 1 was coated directly onto a low carbon steel surface as a primer layer and allowed to cure. The cured coating was then electrically disbonded by the following procedure. A thickened gel comprised of ammonium hexafluoride-exchanged PPODA was spread over the surface of the primer-coating and physically contacted with a conductive element, such as a wire, mesh, foil or grid. Attachment of a 50V power source to the steel surface (anode) and the conductive element (cathode) for a period of less than 20 minutes resulted in anodic disruption of the adhesive bond between the primer and the steel surface.

Example 12. This example describes disbonding of a pigmented coating.

To 100 parts by weight of the material of Example 2, was mixed 65 parts by weight titanium dioxide (rutile) pigment to yield a white paint. This paint can be used to coat aluminum, steel or other metal surfaces. The coating was locally disbonded by contacting a conducting plate, coated with an ionically conducting gel, to the paint surface and attaching the positive pole of a 50-volt power source to the coated substrate and the negative pole of the power source to the conducting plate. After 10-15 minutes, the paint was easily removed from the treated area by light scrapping or peeling.

What is claimed is:

1. An electrochemically disbondable composition having a matrix functionality and an electrolyte functionality, said matrix functionality providing an adhesive bond to a substrate, and said electrolyte functionality providing sufficient ionic conductivity to said composition to support a faradaic reaction at an interface with an electrically conductive surface in contact with said composition,

whereby said adhesive bond is weakened at said interface.

2. The composition of claim 1, wherein said matrix functionality is provided by a polymer.

3. The composition of claim 2, wherein said polymer is selected from the group consisting of epoxies, phenolics, acrylics, melamines, maleimides, and polyurethanes and combinations thereof.

4. The composition of claim 2, wherein said polymer has a variable crosslink density to form regions of low crosslink density having a relatively high ionic conductivity and regions of high crosslink density having a relatively high mechanical strength.

5. The composition of claim 2, wherein said polymer includes coordination sites that are capable of solvating ions and that support the electrolyte functionality of said composition.

6. The composition of claim 5, wherein said coordination sites are selected

from the group consisting of alkoxy moieties, disulfide moieties, thioalkyl moieties, nitrile moieties, and polyvinylidene fluoride moieties and derivatives thereof.

7. The composition of claim 1, wherein said electrolyte functionality is provided in said composition by an electrolyte additive selected from the group consisting of ion solvating molecules, oligomers and polymers, and ionomers.

8. The composition of claim 1 or 7, wherein said electrolyte functionality is localized in regions within said polymer to form a secondary phase with ionic conductivity.

9. The composition of claim 1, wherein said electrochemically disbondable composition is a phase separated material having first regions of substantially matrix functionality and second regions of substantially electrolyte functionality.

10. The composition of claim 9, wherein said first regions comprise a polymer.

11. The composition of claim 10, wherein said polymer is selected from the group consisting of epoxies, phenolics, acrylics, melamines, maleimides, and polyurethanes and combinations thereof.

12. The composition claim 2 or 11, wherein said polymer comprises epoxy.

13. The composition of claim 9, wherein said second regions are selected from the group consisting of ion solvating molecules, oligomers, and polymers and copolymer blocks thereof, and ionomers.

14. The composition of claim 13, wherein said ion solvating molecule is
5 selected from the group consisting of low molecular weight alkoxides, alcohols, alkyl carbonates, cyclic esters, nitriles, amides and ureas.

15. The composition of claim 9, wherein said phase separated material comprises a block or graft copolymer containing non-polar components and components of ionic conductivity.

10 16. The composition of claim 15, wherein said non-polar component of said block copolymer is selected to have a low affinity for said matrix functionality of said composition to facilitate phase separation.

17. The composition of claim 1, further comprising a reservoir for containing curing or crosslinking agent.

15 18. The composition of claim 17, wherein the reservoir is selected from the group consisting of zeolites, clays and polymer gels.

19. The composition of claim 1 or 9, wherein said electrolyte functionality includes a salt capable of being solvated into said composition.

20. The composition of claim 19, wherein said salt is selected from the group consisting of alkali metal, alkaline earth and ammonium salts.

21. The composition of claim 19, wherein said salts include an anion selected from the group consisting of hexafluorophosphate, tetrafluoroborate,
5 hexafluoroantimonate and perchlorate.

22. The composition of claim 19, wherein said salt is an ammonium salt and the ammonium cation is immobilized in said composition.

23. The composition of claim 1 or 9, wherein said composition has a ionic conductivity in the range of 10^{-11} to 10^{-5} S/cm².

10 24. The composition of claim 1 or 9, wherein said composition has a ionic conductivity in the range of 10^{-9} to 10^{-7} S/cm².

25. The composition of claim 1 or 9, further comprising an additive selected from the group consisting of pigments, corrosion inhibitors, leveling agents, gloss promoters, rubber tougheners and fillers.

15 26. The composition of claim 1 or 9, wherein said composition is an adhesive.

27. The composition of claim 26, wherein said adhesive composition has a shear strength with a surface of at least 200 psi.

28. The composition of claim 1 or 9, wherein said composition is a coating.

29. The composition of claim 28, wherein said coating is resistant to delamination from a substrate to which it is applied.

30. An electrochemically disbondable composition, comprising:
5 a curable material having an electrolyte located therein,
wherein said uncured polymeric material, when cured, provides in combination with said electrolyte, sufficient ionic conductivity to support a faradaic reaction at a surface in electrical contact with an electrode.

31. The composition of claim 30, wherein said curable material is selected
10 from the group consisting of epoxy resins, phenolic resins, acrylic resins, melamine resins, maleimide resins, and urethanes.

32. The composition of claim 30, wherein the composition phase separates upon curing, said phase separated material having first regions of mechanical strength and second regions of ionic conductivity.

15 33. A corrosion resistant coating, comprising:
a substrate subject to corrosion; and
a composition having a matrix functionality and an electrolyte functionality, said matrix functionality providing an adhesive bond to said substrate, and said electrolyte functionality providing sufficient ionic conductivity
20 to said composition to support a faradaic reaction at an interface with said

substrate,

whereby corrosion of said substrate does not propagate at said interface.

34. A bonded structure, comprising;
two electrically conductive surfaces; and

5 a bond between said two surfaces, said bond including:
the electrochemically disbondable composition of claim 1 or 9.

35. The bonded structure of claim 34, wherein at least one of said
conductive surfaces is an article to be secured by said bond.

36. The bonded structure of claim 34, wherein at least one of said
10 electrically conductive surfaces comprises a conductive element selected from the
group consisting of sheets, foils, grids and meshes.

37. The bonded structure of claim 35, wherein at least one of said
electrically conductive surfaces comprises a conductive element selected from the
group consisting of sheets, foils, grids and meshes.

15 38. The bonded structure of claim 36, wherein said conductive element
further is bonded to an article using an adhesive.

39. The bonded structure of claim 36, wherein said conductive element
further is bonded to an article using the electrochemically disbondable composition
of claim 1.

40. The bonded structure of claim 34, wherein at least one of said electrically conductive surfaces is an electrically conductive coating applied to a substrate.

41. The bonded structure of claim 36, wherein at least one of said electrically conductive surfaces is an electrically conductive coating applied to a substrate.

42. A bonded structure, comprising;
first and second electrically conductive surfaces; and
an electrically conductive element disposed there between,
10 wherein the electrochemically disbondable composition of claim 1 is used to bond said electrically conductive element to said first and second conductive surfaces.

43. A laminate structure, comprising:
first and second electrically conductive elements selected from the
15 group consisting of foils, sheets, meshes and grids; and
the disbondable composition of claim 1 or 9 disposed therebetween and bonded to said first and second elements.

44. A method of disbonding a composition from an electrically conductive
20 surface to which it is bonded, comprising:
providing a first electrically conductive surface treated with an electrochemically disbondable composition having a matrix functionality and an

electrolyte functionality, said matrix functionality providing an adhesive bond to said first conductive surface, and said electrolyte functionality providing sufficient ionic conductivity to said disbondable composition to support a faradaic reaction at an interface of said first conductive surface and said disbondable composition;

5 contacting a second electrically conductive surface to said disbondable composition; and

 applying a voltage across said disbondable composition to cause a faradaic reaction at said first conductive surface, whereby the bond to said first conductive surface is weakened.

10 45. The method of claim 44, further comprising:
 removing said disbondable composition from said first conductive surface.

46. The method of claim 44, wherein said composition is a coating.

15 47. The method of claim 44, wherein said second electrically conductive surface is an ionically conductive gel.

48. The method of claim 47, whereby said coating in contact with said electrically conducting gel is selectively removed.

49. The method of claim 44, wherein said composition is an adhesive.

50. The method of claim 44, wherein said disbonding occurs at the anodic

interface.

51. The method of claim 44, wherein disbonding occurs at the cathodic interface.

52. The method of claim 44, wherein disbonding takes place at said first and
5 second electrically conductive surfaces.

53. The method of claim 52, wherein an alternating current is applied to said disbonding composition.

54. The method of claim 52, wherein a voltage is applied in a first electrical circuit to disbond at the first electrically conductive surface; and thereafter polarity
10 of the circuit is reversed and an electrical voltage is applied to disbond the composition at the second electrically conductive surface.

55. The method of claim 52, wherein the first and second electrically conductive surfaces are electrically connected in parallel to a power source and voltage is applied is applied between the first and second electrically conductive
15 surfaces and a third electrically conductive surface in contact with the disbondable composition.

56. The method of claim 44, further comprising;
monitoring the current at an ammeter in series with the structure and stopping the applied voltage once current has been reduced by a predetermined

amount.

57. The method of claim 45, further comprising:

contacting said disbondable composition and/or said first conductive surface including residual disbondable composition with a solvent capable of ion solvation to solvate said electrolyte functionality of said disbondable composition, 5 whereby said disbondable composition is removable from said surface.

58. The method of claim 57, wherein said solvent is selected from the group consisting of low molecular weight alcohols.

59. A method of removing a composition from a substrate, comprising:

10 contacting a surface treated with an electrochemically disbondable composition having a matrix functionality and an electrolyte functionality, said matrix functionality providing an adhesive bond to said surface, and said electrolyte functionality providing sufficient ionic conductivity to said disbondable composition to support a faradaic reaction at an interface of said first electrically 15 conductive surface and said disbondable composition, with a solvent capable of ion solvation,

whereby ions of said electrolyte functionality are solvated; and removing said composition from said surface.

ELECTRICALLY DISBONDING MATERIALS

Abstract of the Disclosure

An electrochemically disbondable composition is provided having a matrix functionality and an electrolyte functionality. The matrix functionality provides an adhesive bond to a substrate, and the electrolyte functionality provides sufficient ionic conductivity to the composition to support a faradaic reaction at an interface with an electrically conductive surface in contact with the composition, whereby the adhesive bond is weakened at the interface. The composition may be a phase-separated composition having first regions of substantially matrix functionality and second regions of substantially electrolyte functionality. Adhesive and coating compositions and methods of disbonding also are described.

\\Ceserver\documents\50126\50126 002001 disbondable material application.wpd

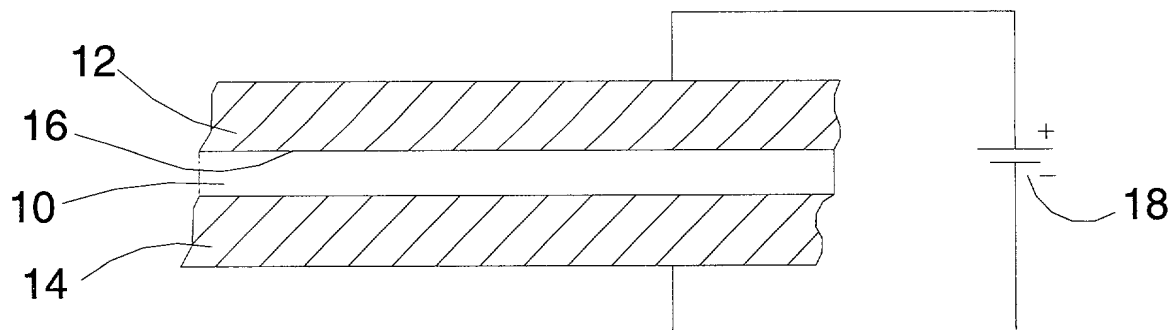


Figure 1

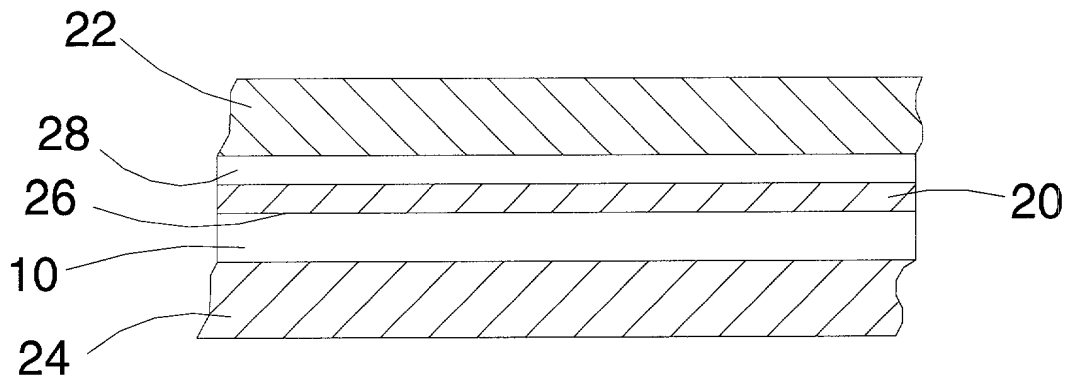


Figure 2

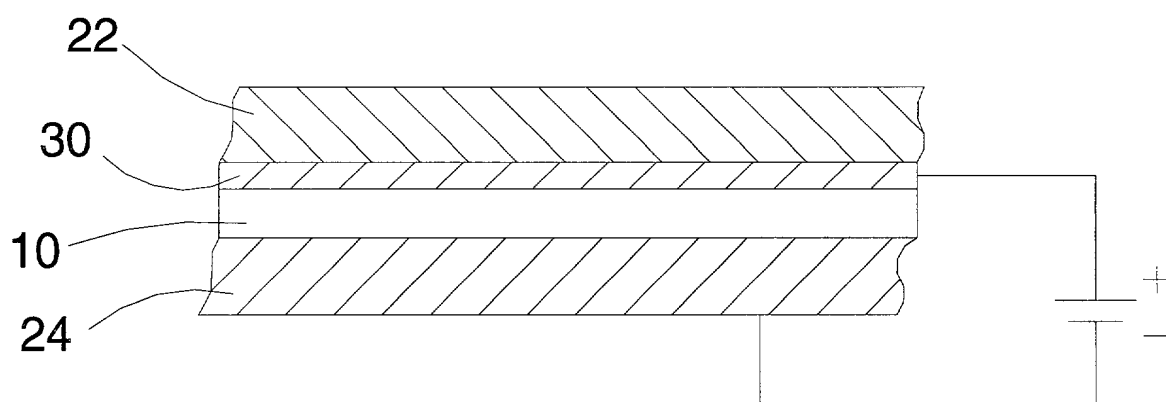


Figure 3

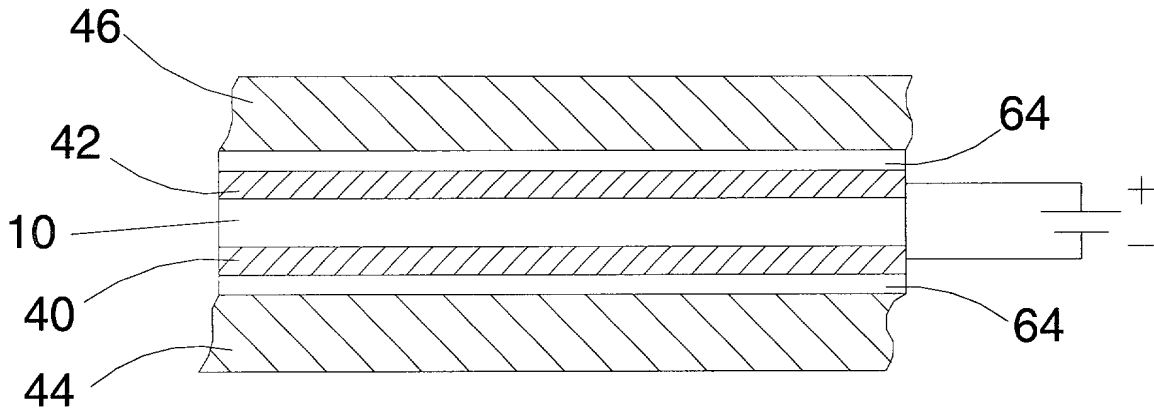


Figure 4A

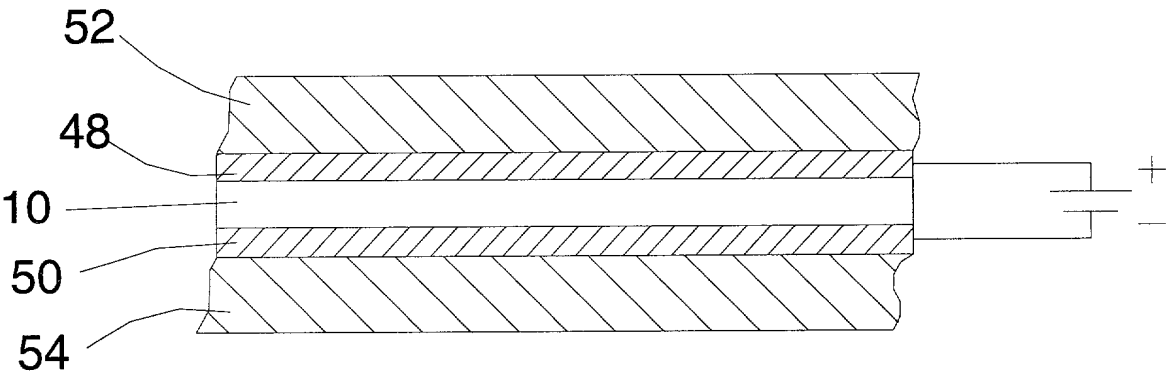


Figure 4B

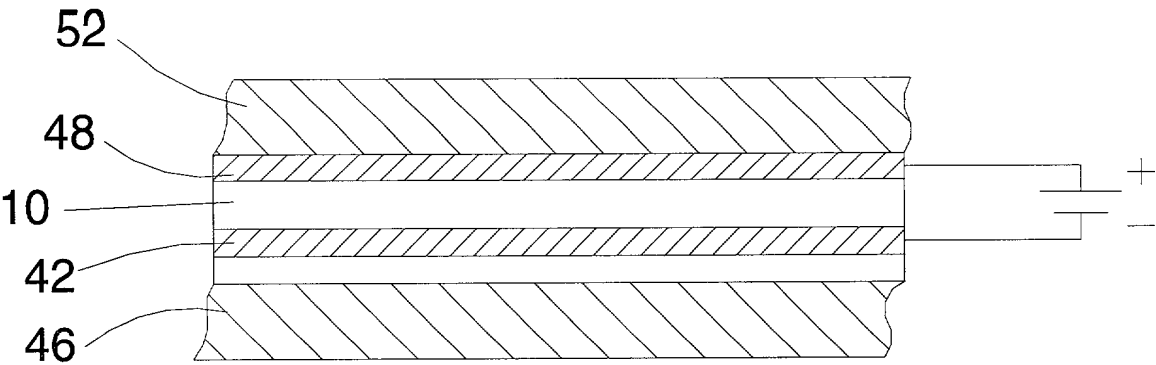


Figure 4C

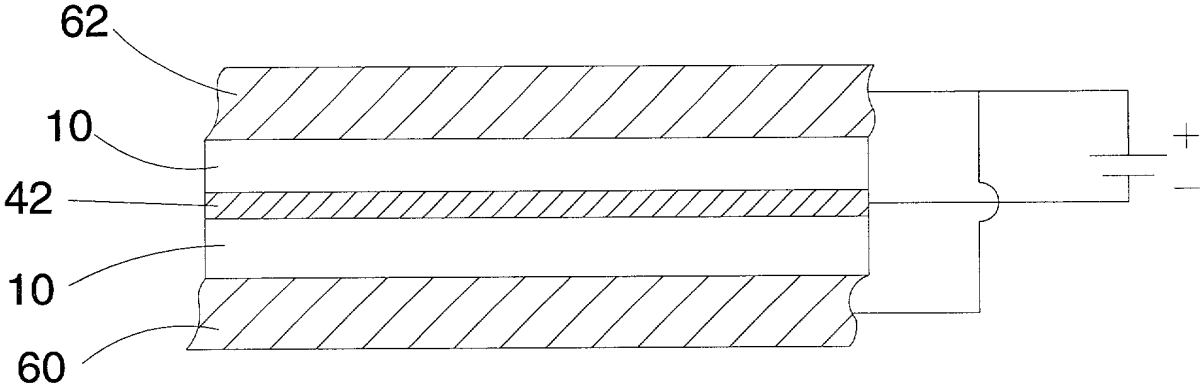


Figure 5

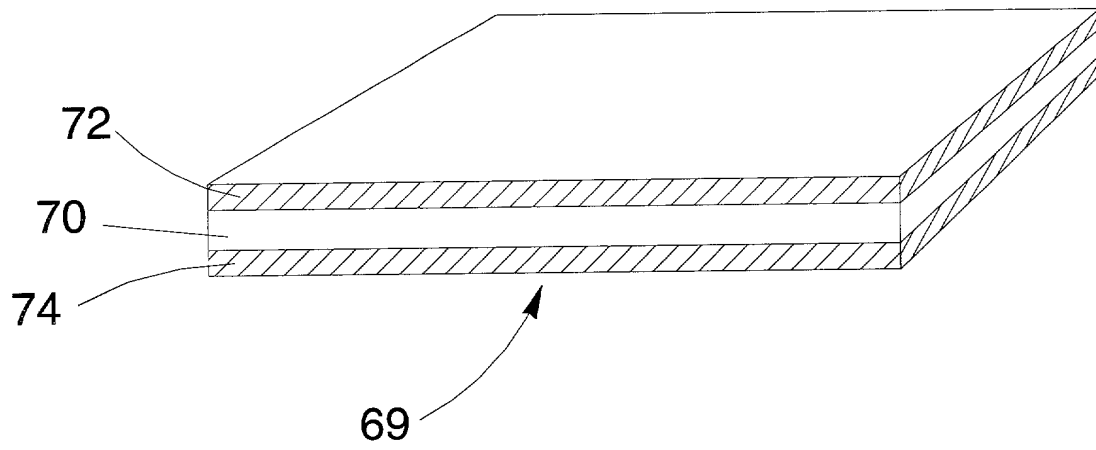


Figure 6A

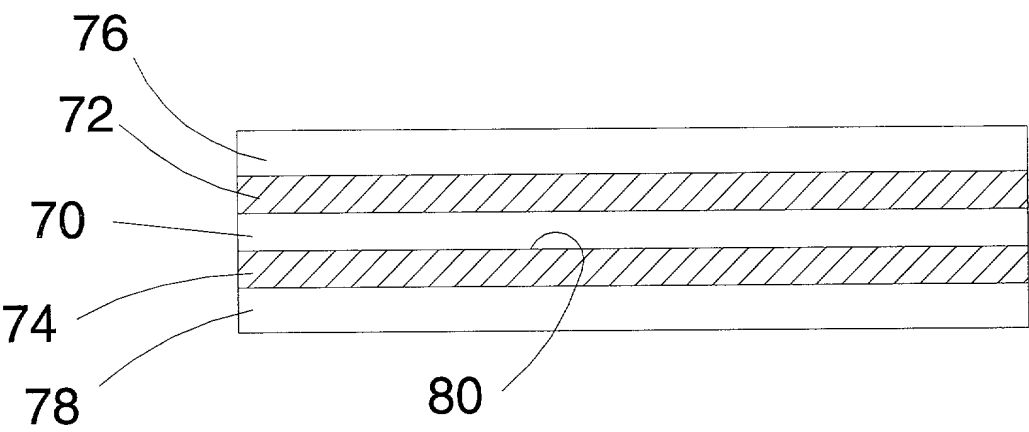


Figure 6B

COMBINED DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled ELECTRICALLY DISBONDING MATERIALS, the specification of which

- ☒ is attached hereto.
- ☐ was filed on _____ as Application Serial No. _____
and was amended on _____.
- ☐ was described and claimed in PCT International Application No. _____
filed on _____ and as amended under PCT Article 19 on _____.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose all information I know to be material to patentability in accordance with Title 37, Code of Federal Regulations, §1.56(a).

I hereby claim foreign priority benefits under Title 35, United States Code, §119 of any foreign application(s) for patent or inventor's certificate or of any PCT international application(s) designating at least one country other than the United States of America listed below and have also identified below any foreign application for patent or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed by me on the same subject matter having a filing date before that of the application(s) of which priority is claimed:

Country	Serial Number	Filing Date	Priority Claimed?
			Yes/No
			Yes/No
			Yes/No

I hereby claim the benefit under Title 35, United States Code, §120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, §112, I acknowledge the duty to disclose all information I know to be material to patentability as defined in Title 37, Code of Federal Regulations, §1.56(a) which became available between the filing date of the prior application and the national or PCT international filing date of this application:

COMBINED DECLARATION AND POWER OF ATTORNEY

Serial Number	Filing Date	Status

I hereby appoint the following attorneys and/or agents to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith: Paul T. Clark, Reg. No. 30,162, Karen L. Elbing, Ph.D. Reg. No. 35,238, Kristina Bieker-Brady, Ph.D. Reg. No. 39,109, Susan M. Michaud, Ph.D. Reg. No. 42,885, Mary Rose Scozzafava, Ph.D., Reg. No.36,268, James D. DeCamp, Ph.D., Reg. No. 43,580.

Address all telephone calls to: Mary Rose Scozzafava at 617/428-0200.

Address all correspondence to: Mary Rose Scozzafava at Clark & Elbing LLP, 176 Federal Street, Boston, MA 02110.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Full Name (First, Middle, Last)	Residence Address (City, State, Country)	Post Office Address (Street, City, State, Country)	Citizenship
Michael D. Gilbert	8 Westview Road Brookline, NH 03033	SAME	USA
Signature: <i>Michael D. Gilbert</i>			Date: <i>7 July 99</i>